

## STD40NF03L

PRELIMINARY DATA

## N-CHANNEL 30V - 0.0095 Ω - 40A DPAK LOW GATE CHARGE STripFET<sup>TM</sup> POWER MOSFET

ТҮРЕ	V <sub>DSS</sub>	R <sub>DS(on)</sub>	Ι <sub>D</sub>
STD40NF03L	30 V	< 0.012 Ω	40 A

- TYPICAL RDS(on) = 0.0095 Ω
- TYPICAL Q<sub>q</sub> = 35 nC @ 10V
- OPTIMAL RDS(on) x Qg TRADE-OFF
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

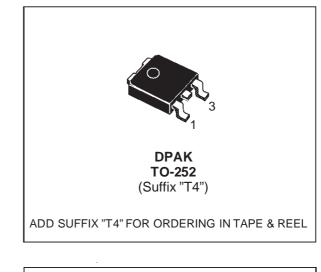
#### DESCRIPTION

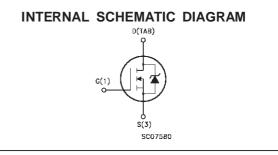
This application specific Power Mosfet is the third generation of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

#### **APPLICATIONS**

SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY CPU CORE DC/DC CONVERTERS

**ABSOLUTE MAXIMUM RATINGS** 





Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
V <sub>DGR</sub>	Drain- gate Voltage ( $R_{GS}$ = 20 k $\Omega$ )	30	V
V <sub>GS</sub>	Gate-source Voltage	± 20	V
$I_D(\bullet)$	Drain Current (continuous) at T <sub>c</sub> = 25 °C	20	A
ID	Drain Current (continuous) at T <sub>c</sub> = 100 <sup>o</sup> C	20	A
I <sub>DM</sub> (●●)	Drain Current (pulsed)	80	A
P <sub>tot</sub>	Total Dissipation at $T_c = 25 \ ^{\circ}C$	55	W
	Derating Factor	0.37	W/ºC
Tstg	Storage Temperature	-65 to 175	°C
Τ <sub>i</sub>	Max. Operating Junction Temperature	175	°C

(••) Pulse width limited by safe operating area

#### September 2000

#### THERMAL DATA

Γ	R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	2.73	°C/W
	R <sub>thj-amb</sub>	Thermal Resistance Junction-ambient	Max	62.5	°C/W
	Ť	Maximum Lead Temperature For Soldering	Purpose	300	°C

# **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25 \ ^{o}C$ unless otherwise specified) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A$ $V_{GS} = 0$	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating$ $T_c = 125 °C$			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	$V_{GS} = \pm 20 V$			± 100	nA

#### ON (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \ \mu A$	1			V
R <sub>DS(on)</sub>	Static Drain-source On Resistance			0.0095 0.019	0.012 0.022	Ω Ω
I <sub>D(on)</sub>	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10 V$	40			A

#### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_{D} = 20 \text{ A}$		40		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 V$ f = 1 MHz $V_{GS} = 0$		1470 490 110		pF pF pF

#### ELECTRICAL CHARACTERISTICS (continued)

#### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time			20 170		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 24 V I_D = 40 A V_{GS} = 10 V$		35 5 10	45	nC nC nC

#### SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time			40 60		ns ns

#### SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (●)	Source-drain Current Source-drain Current (pulsed)				20 80	A A
V <sub>SD</sub> (*)	Forward On Voltage	$I_{SD} = 20 \text{ A}  V_{GS} = 0$			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$I_{SD} = 20 \text{ A}$ di/dt = 100 A/µs $V_{DD} = 15 \text{ V}$ $T_i = 150 ^{\circ}\text{C}$		70		ns
Q <sub>rr</sub>	Reverse Recovery Charge	(see test circuit, fig. 5)		105		nC
I <sub>RRM</sub>	Reverse Recovery Current			2.4		A

(\*) Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %
(•) Pulse width limited by safe operating area

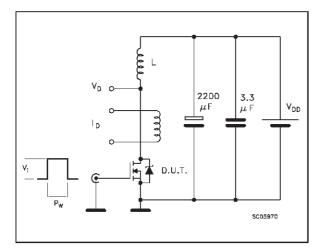
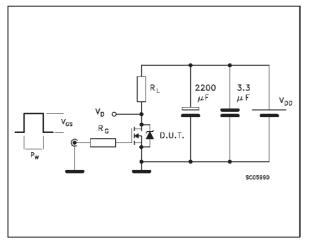
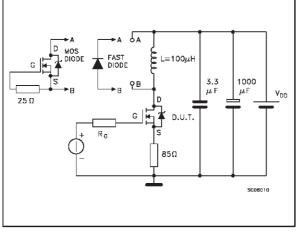


Fig. 1: Unclamped Inductive Load Test Circuit

**Fig. 3:** Switching Times Test Circuits For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



#### Fig. 2: Unclamped Inductive Waveform

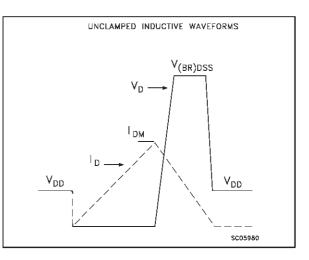
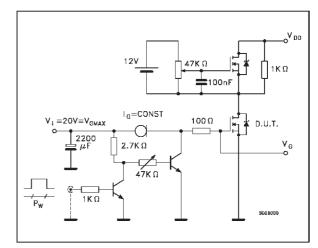


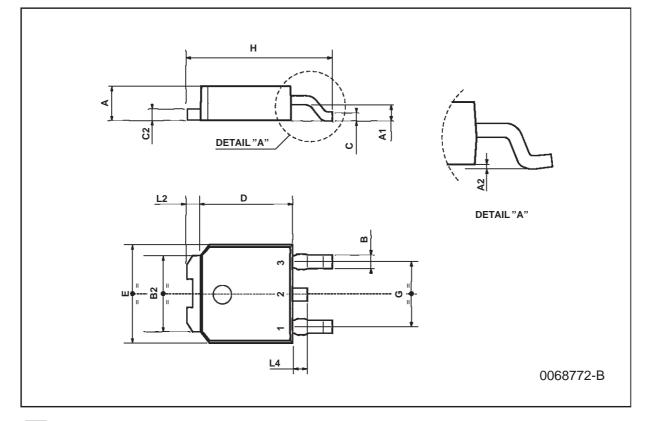
Fig. 4: Gate Charge test Circuit



57

DIM.		mm				
Dim.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
В	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
С	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
Н	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039

### TO-252 (DPAK) MECHANICAL DATA



57

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specification mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics. The ST logo is a trademark of STMicroelectronics

© 2000 STMicroelectronics – Printed in Italy – All Rights Reserved

STMicroelectronics GROUP OF COMPANIES Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia - Malta - Morocco -Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

http://www.st.com

